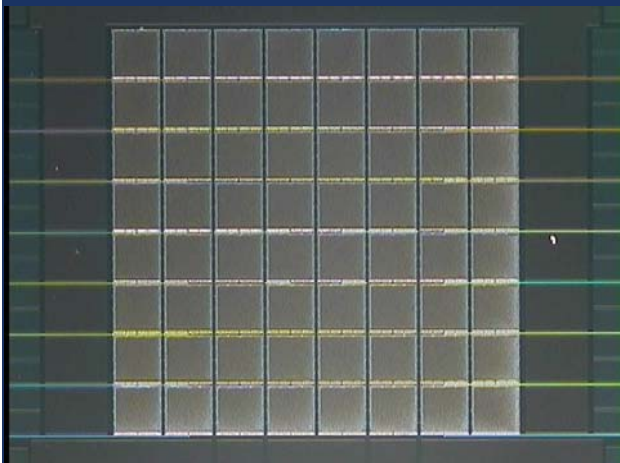


Bolometer Arrays for High-Resolution Spectroscopy

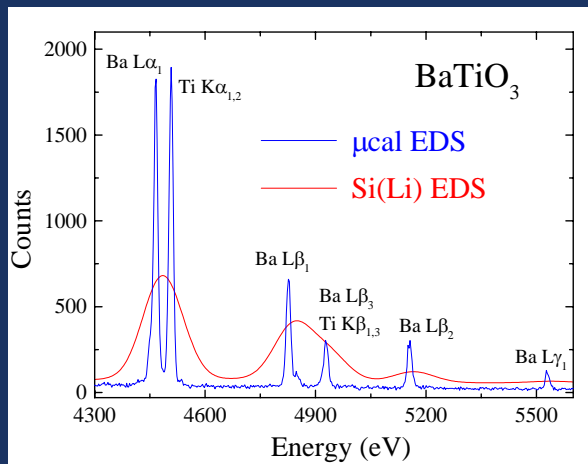


64-pixel x-ray
microcalorimeter array

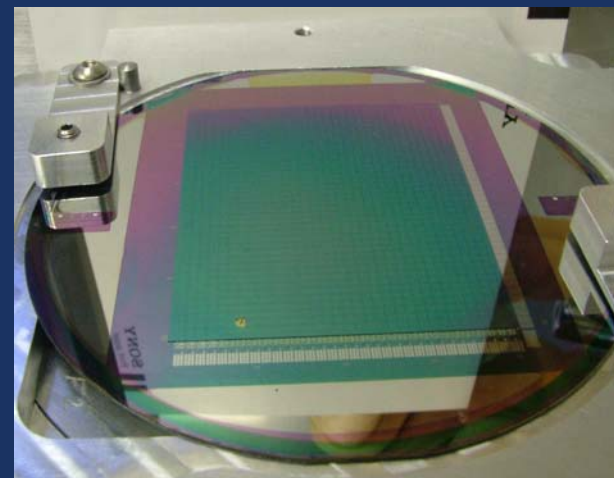
Kent Irwin, NIST

Microcalorimeters: no gap, no Fano limit, thermal fluctuations

STJs: a gap much smaller than semiconductors (Friedrich)



Microcalorimeter x-ray
spectrum of BaTiO₃



1,280-pixel bump
bonded array for
THz

- Microcalorimeters and bolometers
- Multiplexed readout
- Soft and hard x-ray results
- Cryogenics
- The future: 4 possible arrays for synchrotron applications
- Emerging microwave readout techniques

NIST staff

NIST Boulder:

James Beall

Randy Doriese

William Duncan

Lisa Ferreira

Gene Hilton

Rob Horansky

Kent Irwin

Ben Mates

Nathan Miller

Galen O'Neil

Carl Reintsema

Dan Schmidt

Joel Ullom

Leila Vale

Yizi Xu

NIST Gaithersburg:

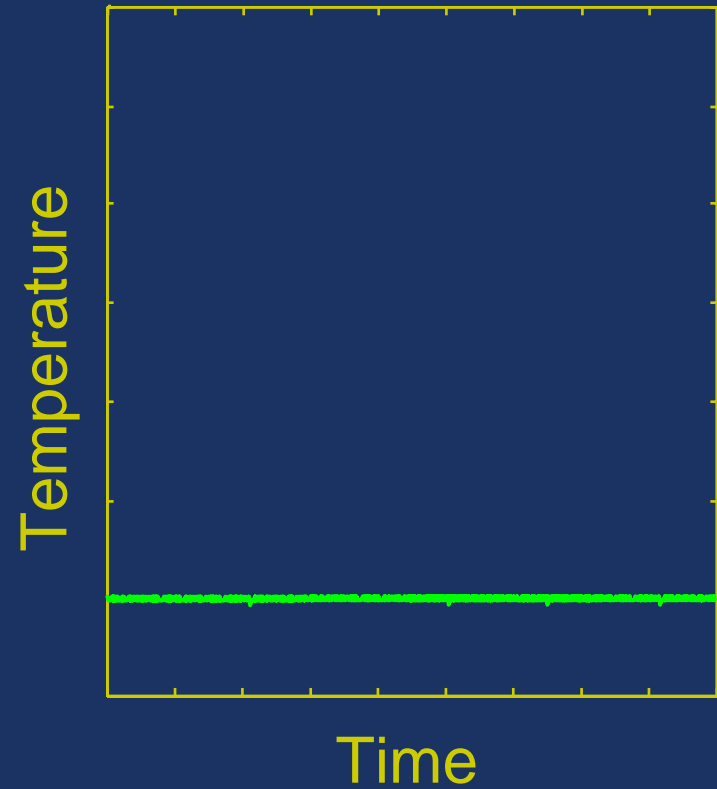
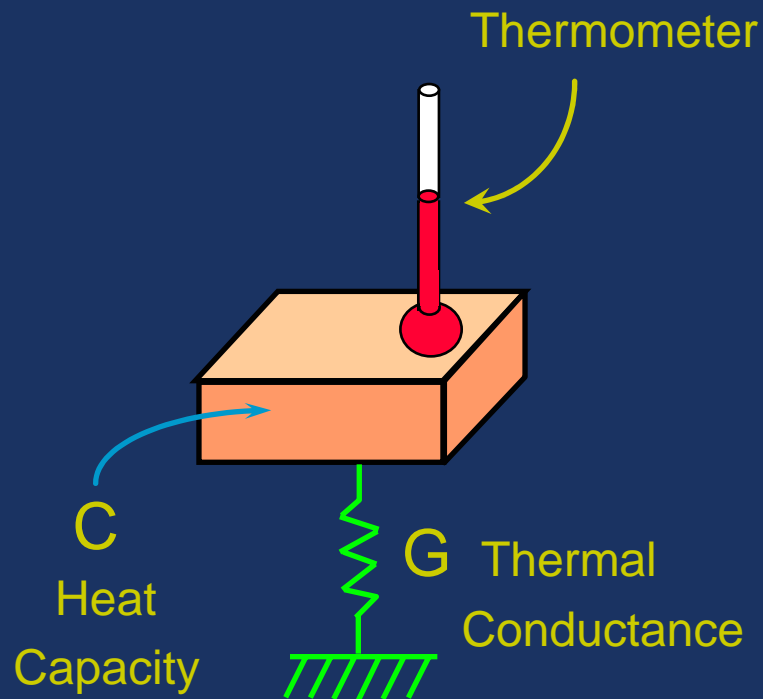
Dale Newbury

Terry Jach

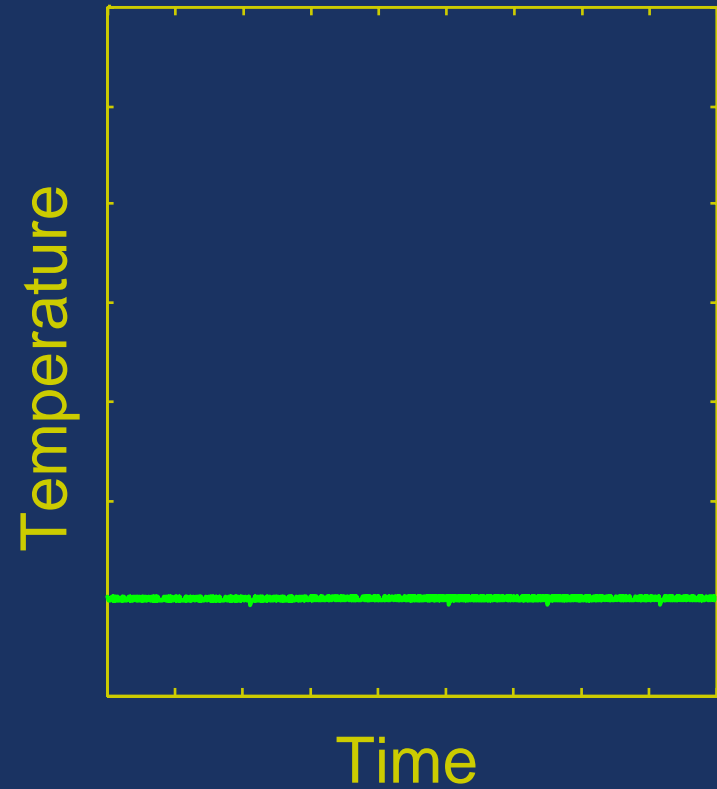
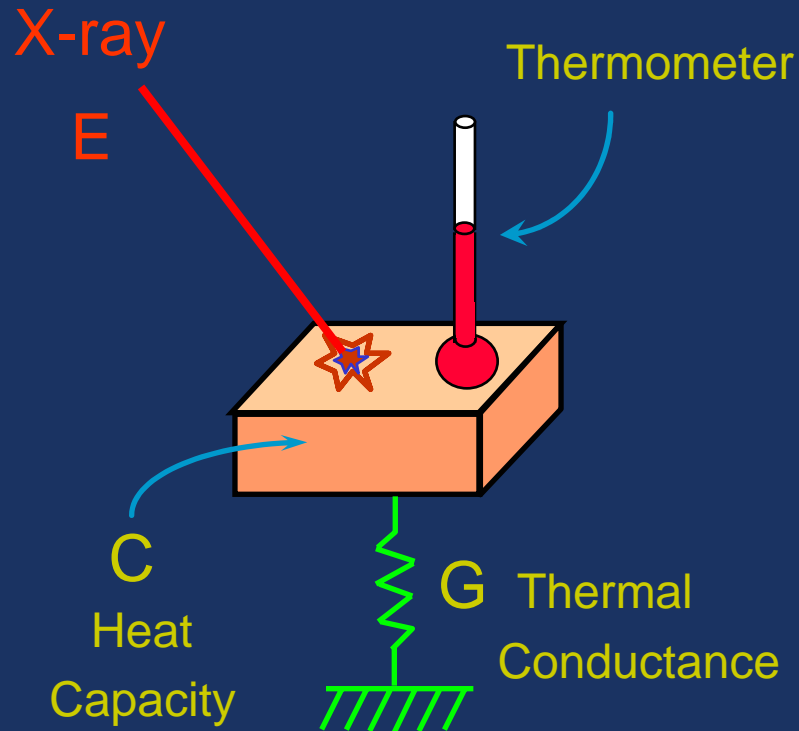
John Small



Bolometers / Microcalorimeters

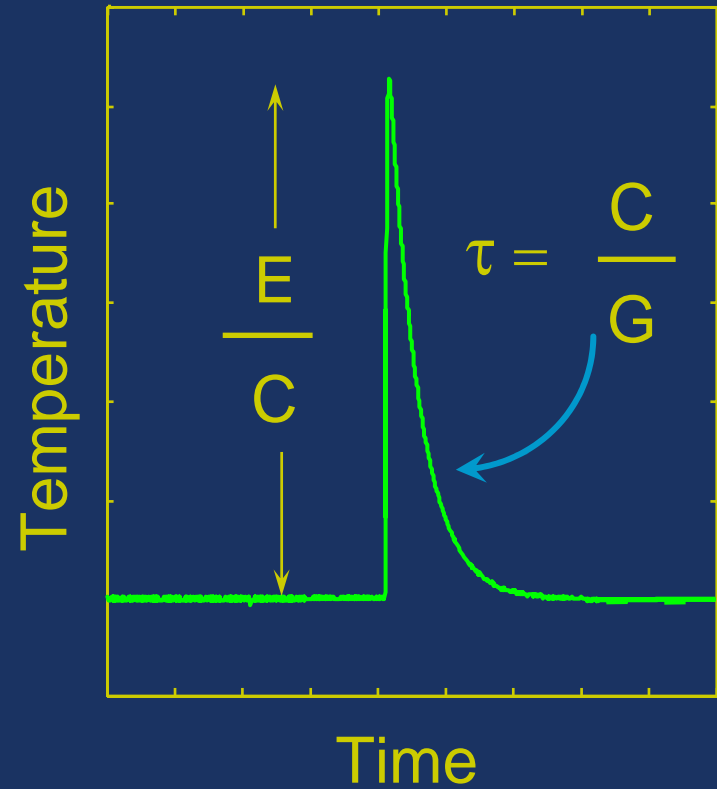
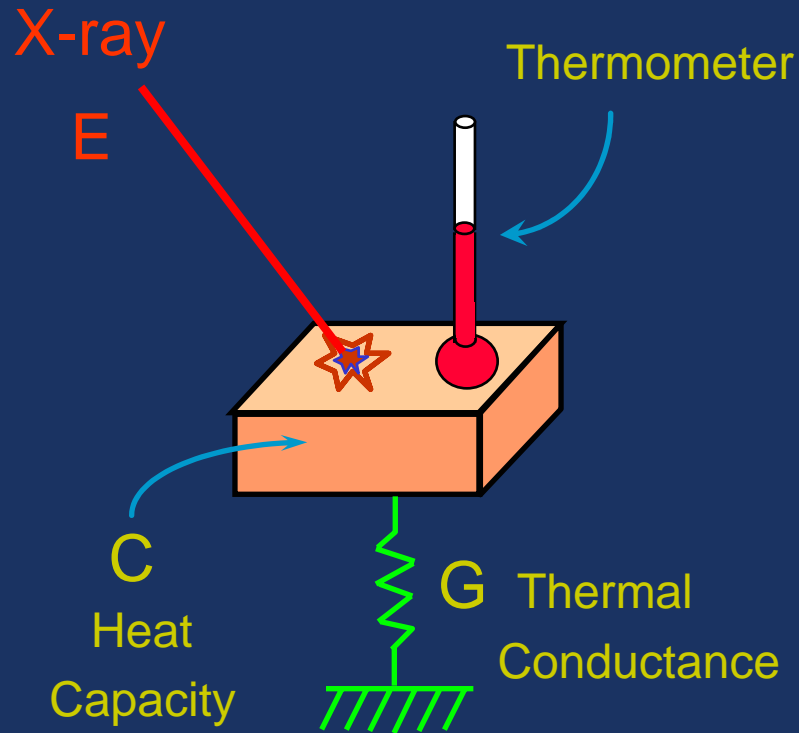


Bolometers / Microcalorimeters



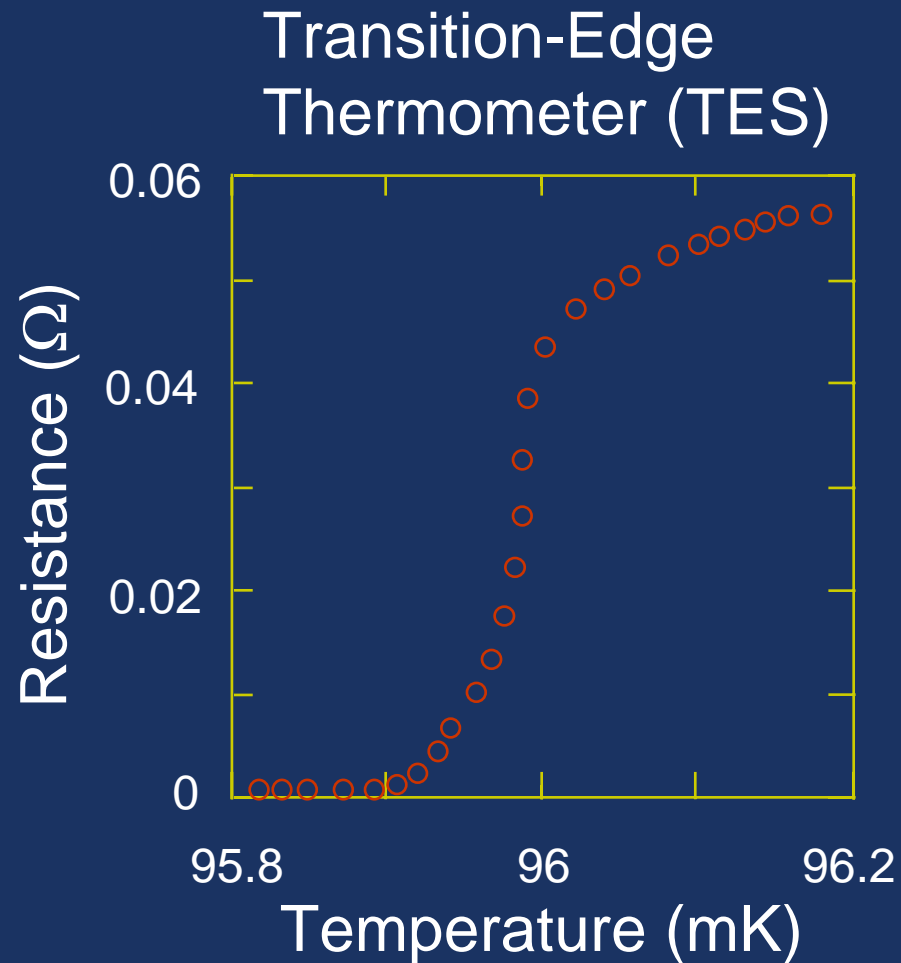
Photon

Bolometers / Microcalorimeters



Photon \rightarrow Heat

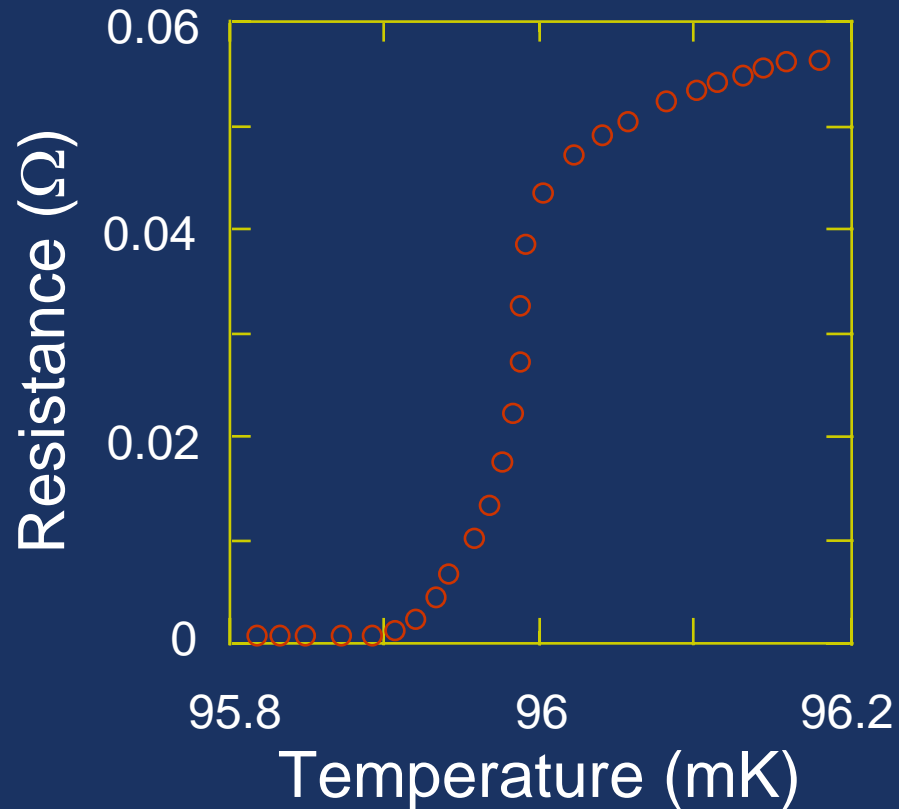
Superconducting Transition-Edge Thermometer



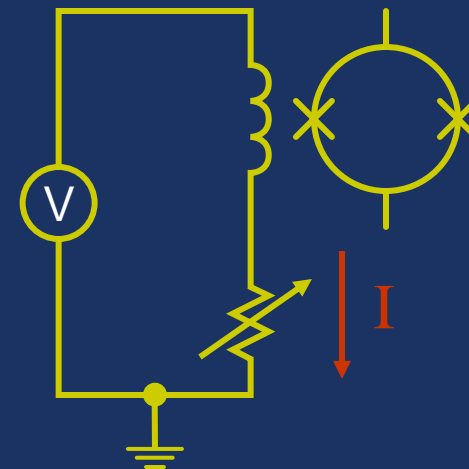
Photon \rightarrow Heat \rightarrow Resistance

Superconducting Transition-Edge Thermometer

Transition-Edge
Thermometer (TES)

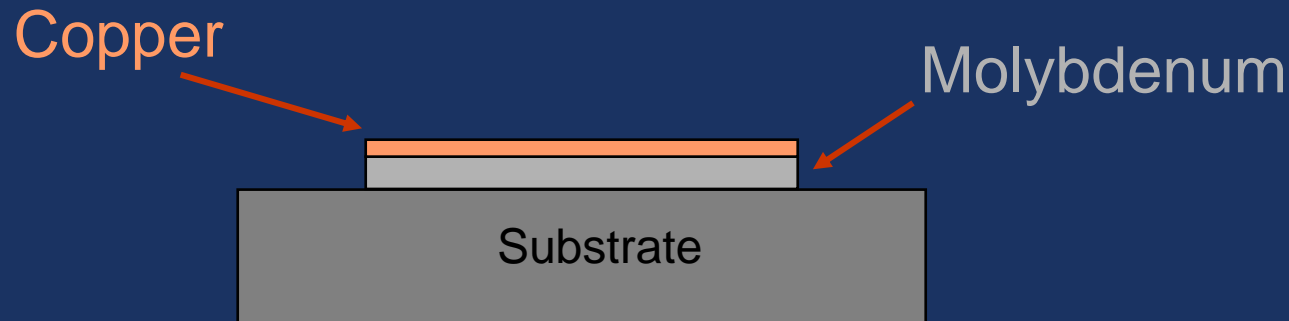


SQUID Current Amplifier



Photon \rightarrow Heat \rightarrow Resistance \rightarrow Current

Molybdenum-Copper Bilayer TES



- A bilayer of a thin superconducting film and a thin normal metal acts as a single superconductor with a tunable T_c - the “proximity effect”
- Molybdenum-copper
 - Robust and temperature stable
 - Molybdenum $T_c \sim .92$ K
 - Copper normal

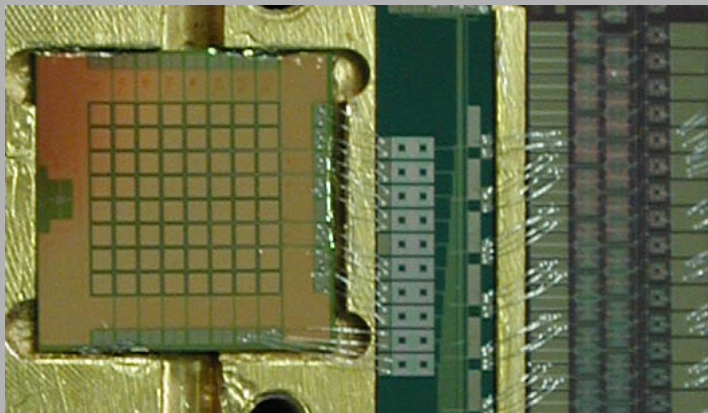
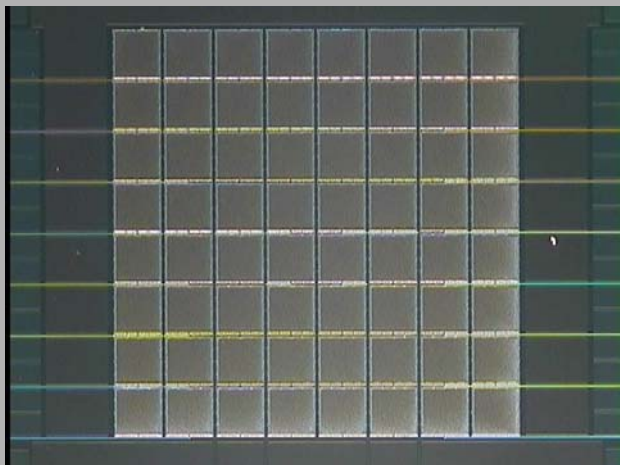
NIST Superconducting Clean Room Facility



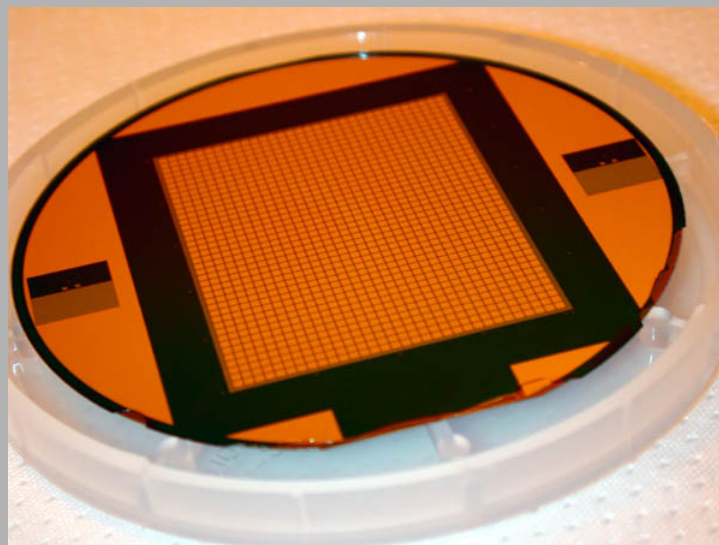
- 2700 sq ft class 100 dedicated superconducting integrated circuit / MEMS space
- I-line 5x lithography
- Niobium trilayer system
- Mo-Cu TES bilayer system
- ECR PECVD deposition
- Bosch “deep” RIE
- XeF₂ etch system
- E-beam lithography
- Reticle generation
- Sputter deposition (x2)
- LPCVD (x2)
- Thermal oxide / diffusion (x2)
- Thermal deposition (x2)
- RIE (x2)
- Plasma etching
- Ion mill etching

TES Fabrication

64-pixel microcalorimeter array



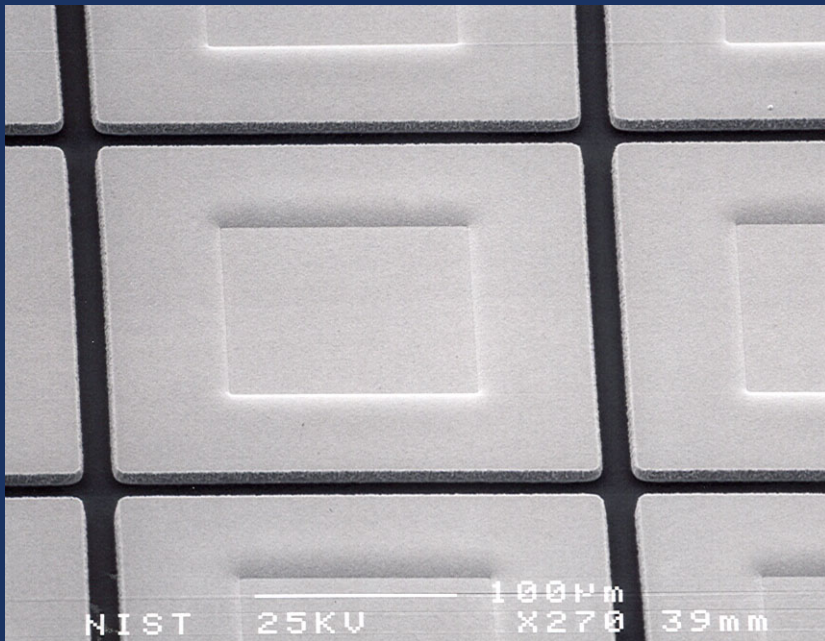
1,280-pixel SCUBA-2 subarray



TES + soft x-ray absorbers

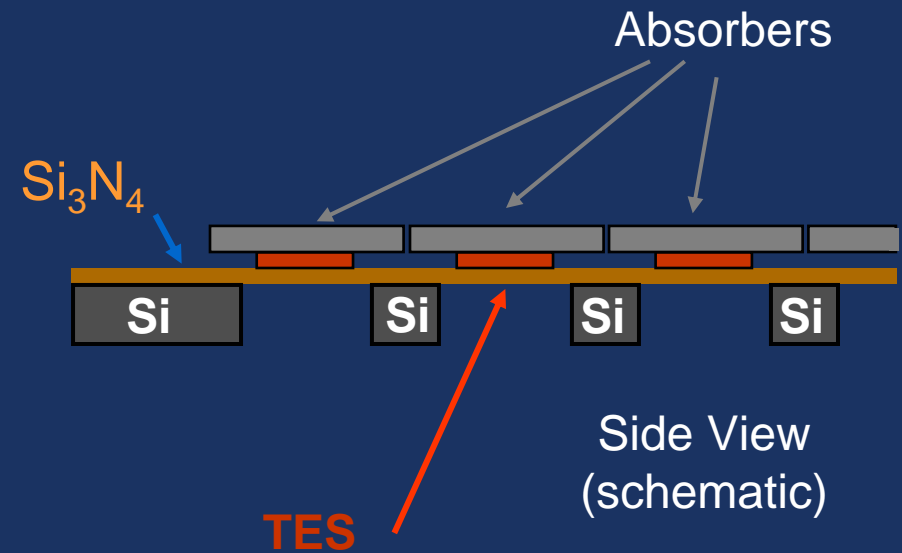


Side View
(SEM)

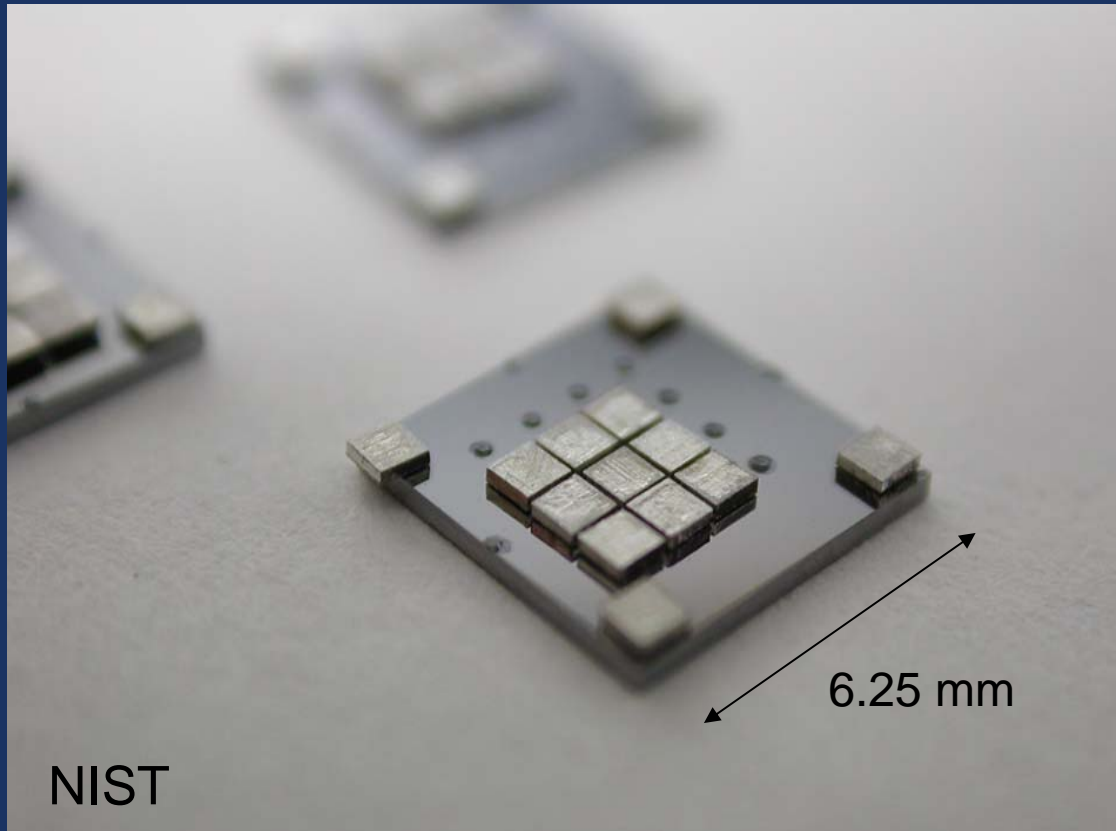


250 μm pixels
6.7 μm thick Bismuth

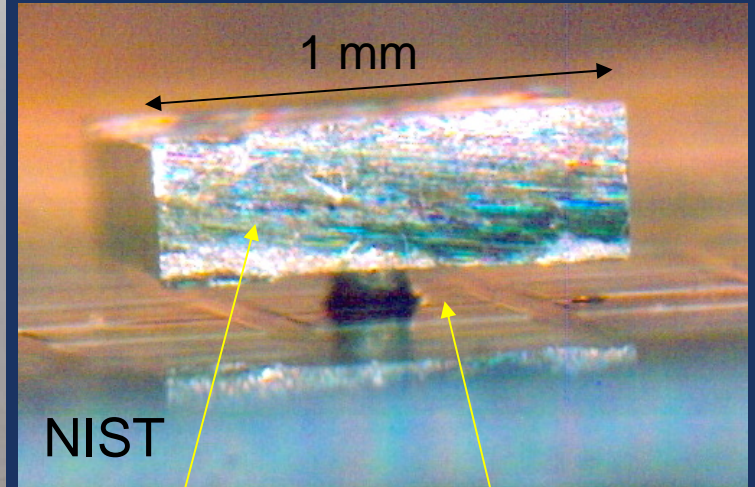
Top View
(SEM)



TES + hard x-ray / γ -ray absorbers



1 mm pixels
250 μm thick Tin



Sn absorber

Mo/Cu TES

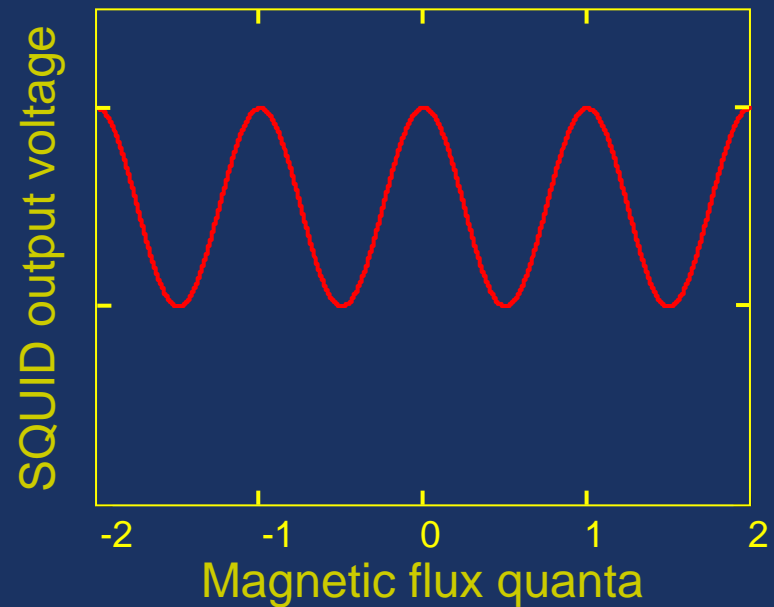
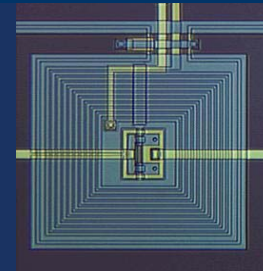
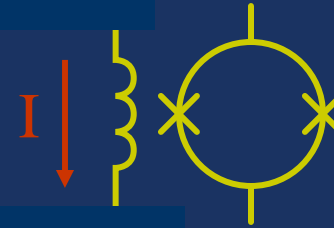
Prior work at LLNL:

e.g. T. Miyazaki et al., *IEEE Trans. App. Super.*, 13 630 (2003)

SQUIDS

SQUID Current Amplifier

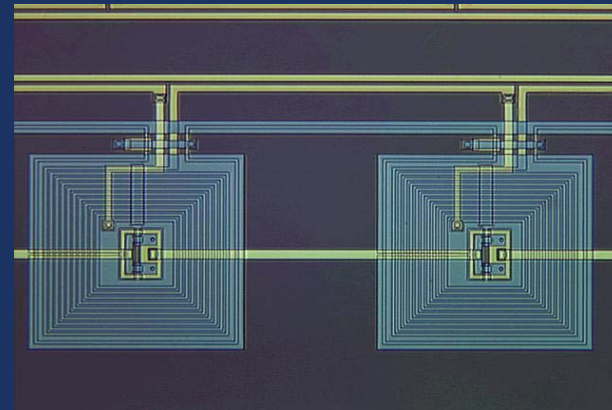
- Superconducting Quantum Interference Devices
- The most sensitive devices for the measurement of magnetic fields.
- SQUIDs operate by quantum interference between two Josephson tunnel junctions
- The output voltage is a periodic function of the applied magnetic flux.



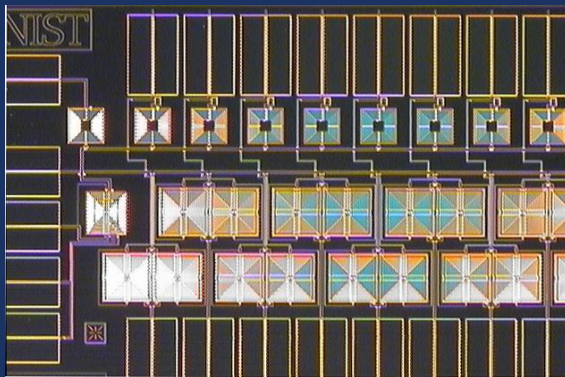
SQUID Fabrication

- Nb/Al/Al₂O₃/Nb trilayer technology
- Low temperature (30 C) ECR PECVD SiO₂
- Two wiring and dielectric levels
- PdAu shunt and damping resistors
- 10 lithography levels

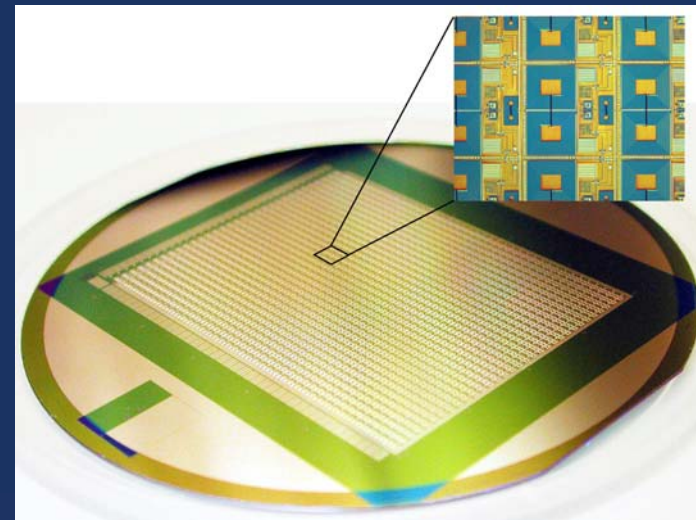
100-SQUID Series Array for the Cryogenic Dark Matter Search



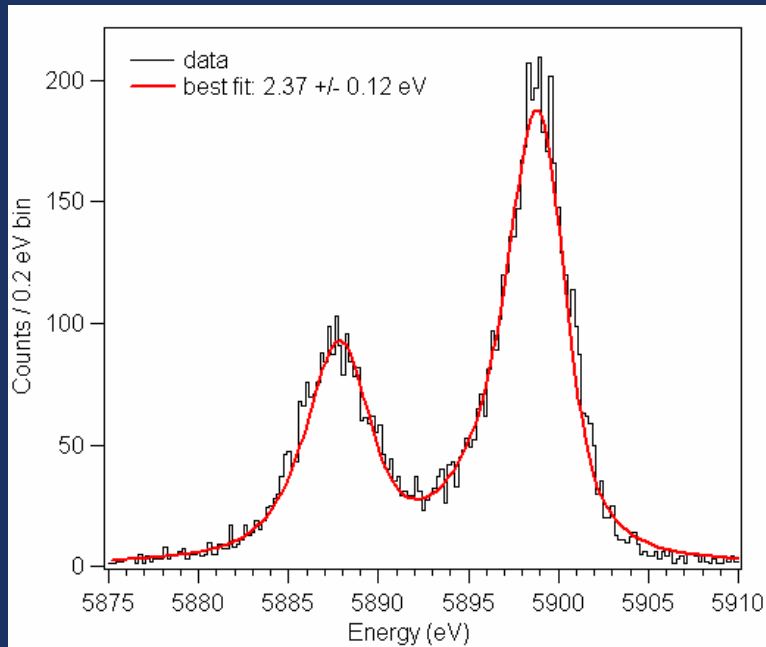
1 × 32 MUX Array



1,280-pixel MUX Array for SCUBA-2



Bolometric energy resolution



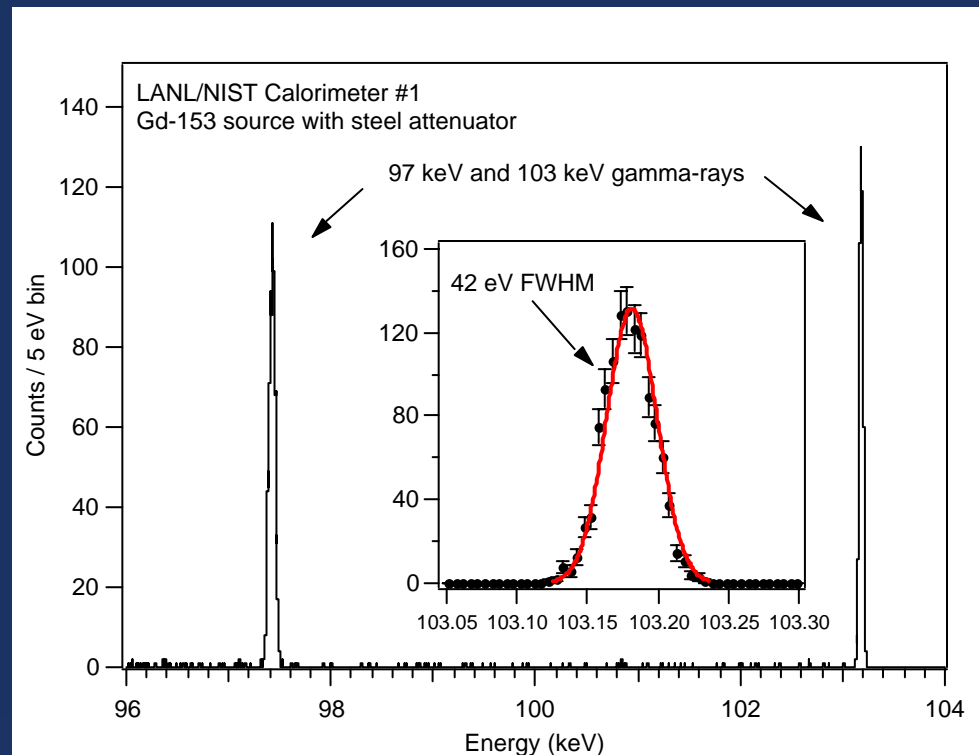
2.4 eV at 5.9 keV Mn K α



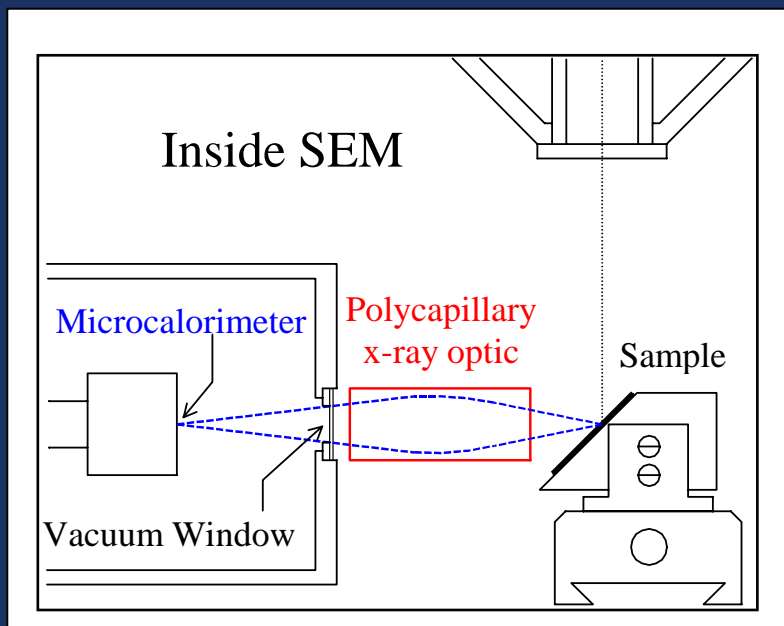
42 eV at 103 keV



Should be able to do
< 1 eV at < 1 keV

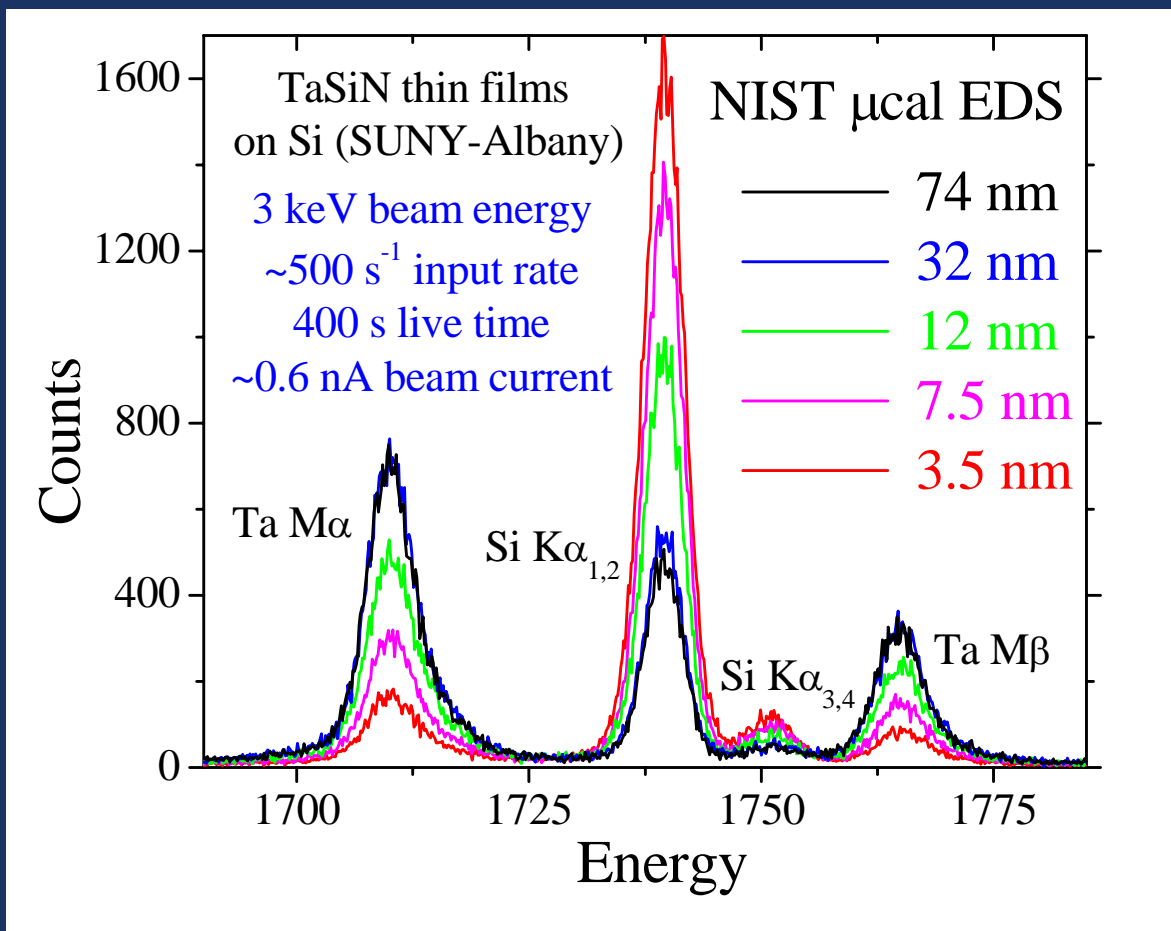


Microanalysis system on SEM



Thin-Film Analysis

The high energy resolution of the microcalorimeter also provides a high peak-to-background ratio, allowing better thin film & trace element analysis



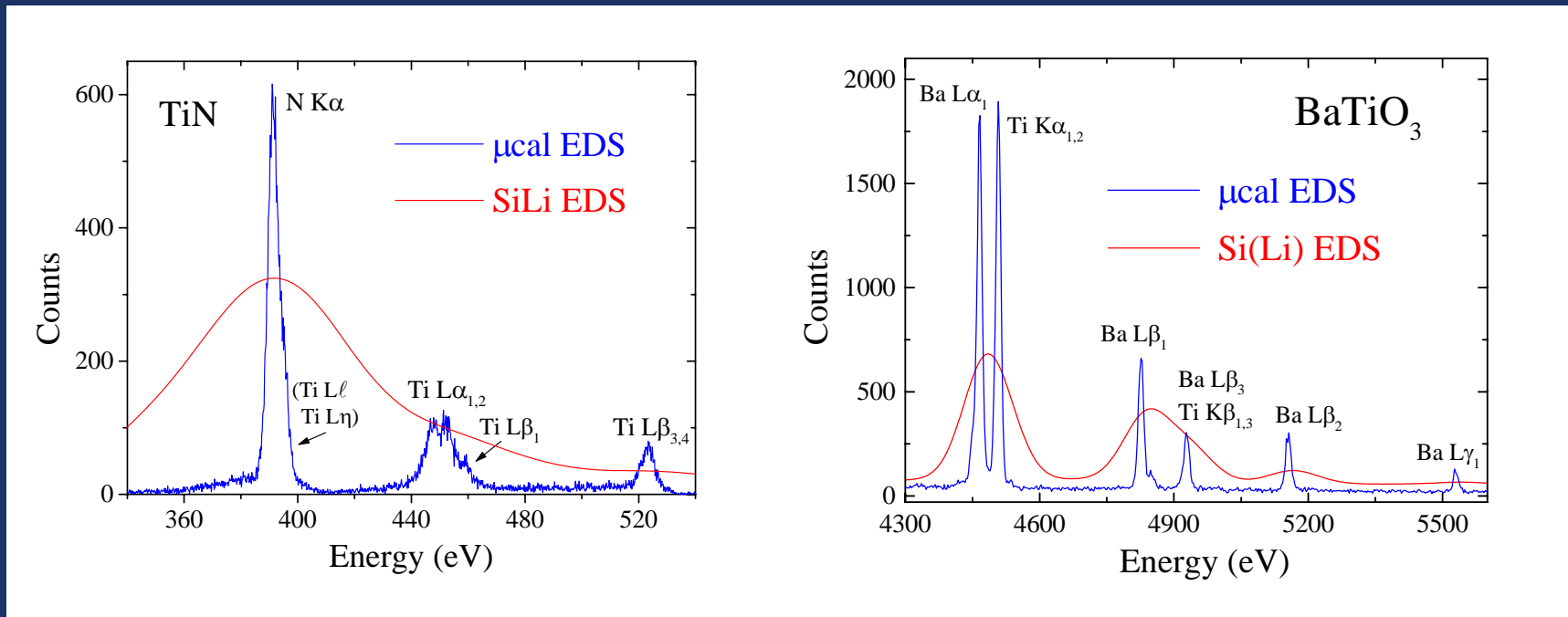
Ref. Geer et. al.

Nanoscale Particle Analysis

- Contaminant particles in semiconductor processing lower yield
- Low beam energies to localize x-ray production in ~60 nm particle
- High energy resolution to resolve overlapping x-ray lines



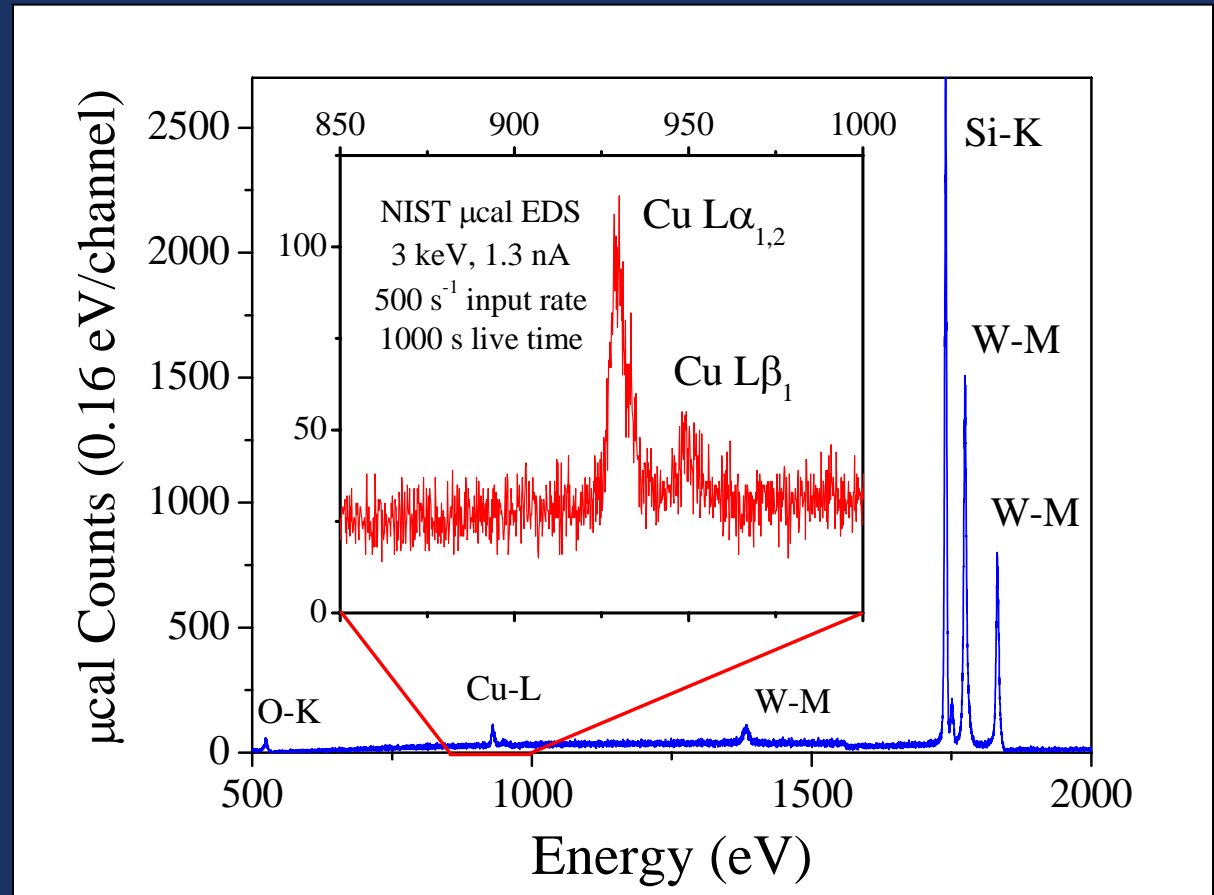
Resolving peak overlaps



Trace-Element Analysis

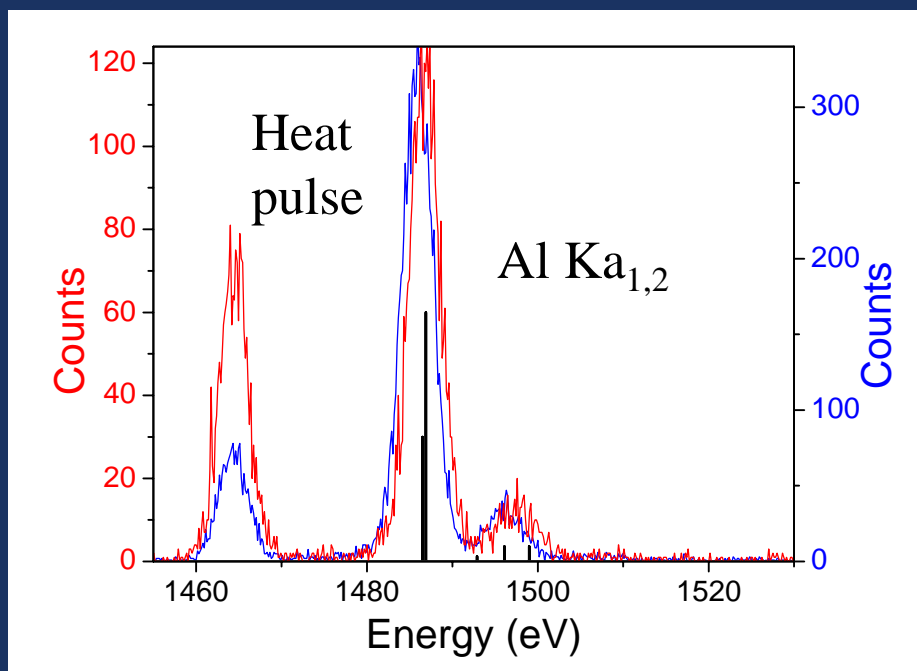
The high energy resolution of the microcalorimeter also provides a high peak-to-background ratio, allowing better thin film & trace element analysis

**0.7 wt. % Cu
measured in WSi_2
thin film**



Collaboration with Vartuli and Stevie (Lucent)

Chemical shift analysis



- Chemical bonding state causes small (< 1 eV) shifts in x-ray line position
- Industrially important problem: Al particles on oxide substrates.



Al oxide particle

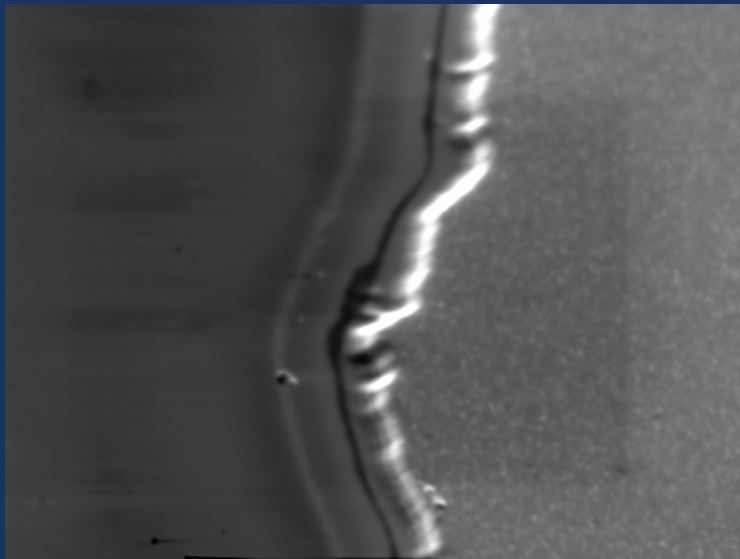


1 μ m 25000X

Al particle

Particle samples provided by
Alain Diebold (SEMATECH)

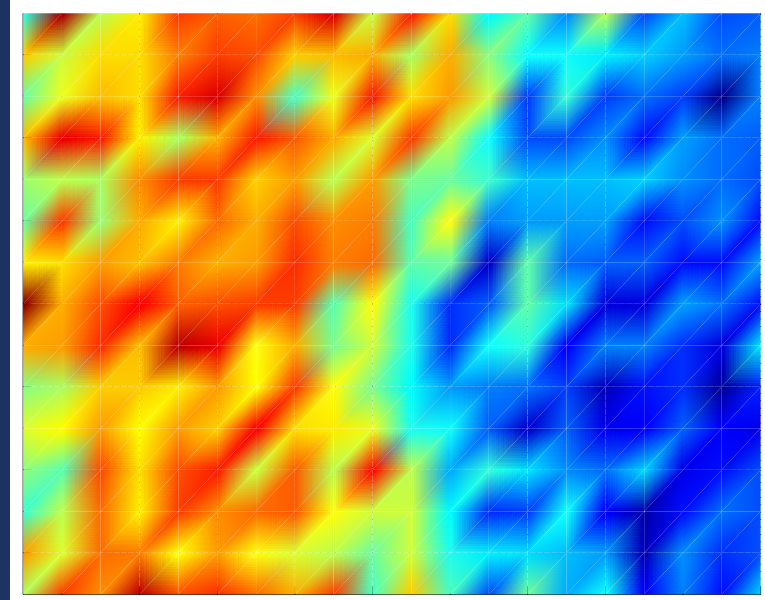
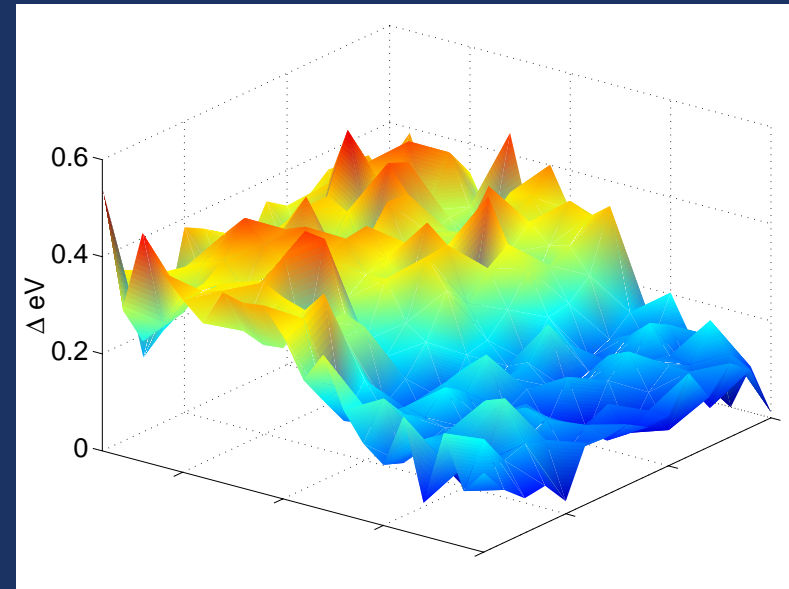
Chemical shift map



10 μ m 2000X

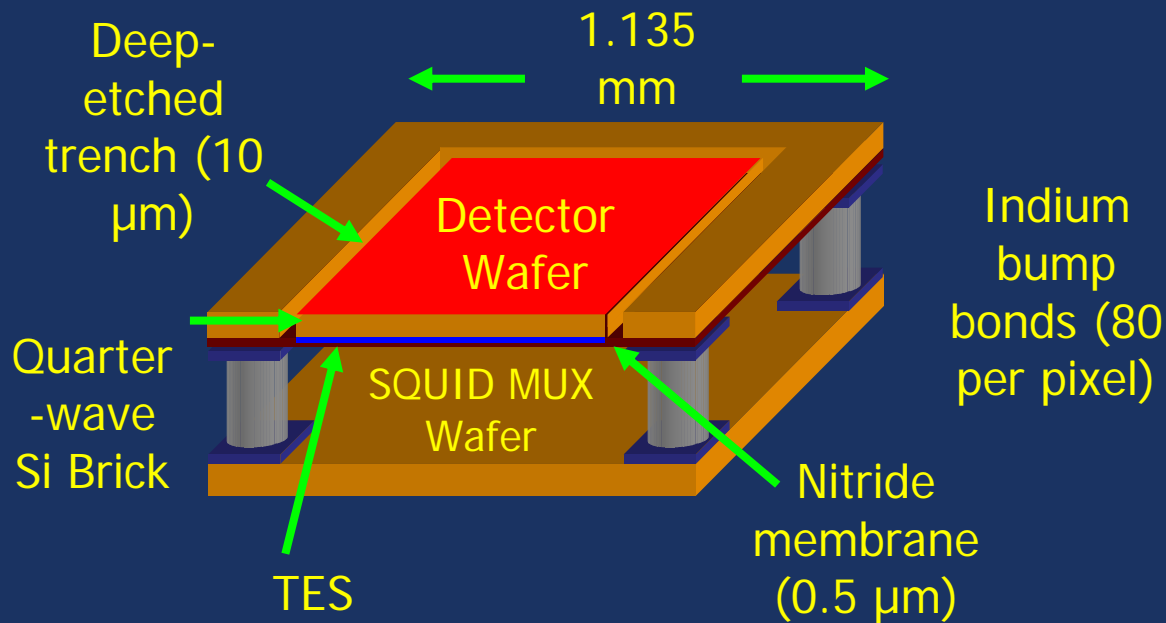
Al oxide

Al

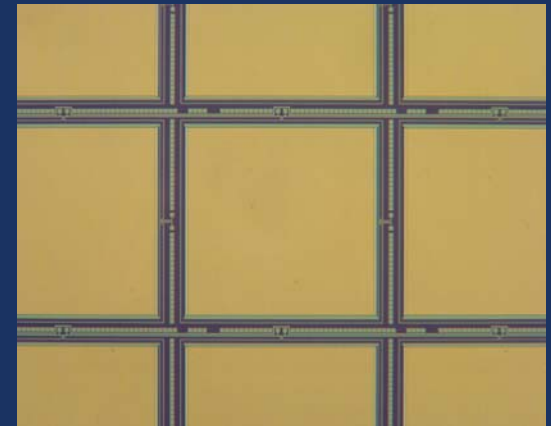


Multiplexed THz bolometer array: SCUBA-2

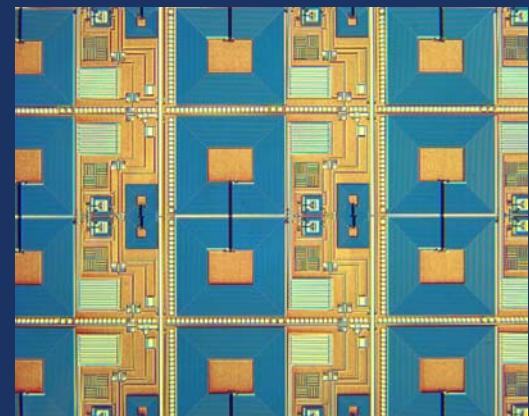
A superconducting pixel detector?



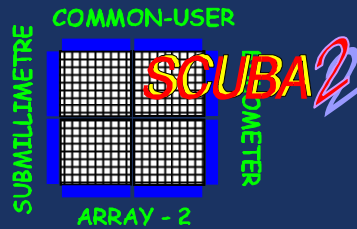
TES bolometer pixels



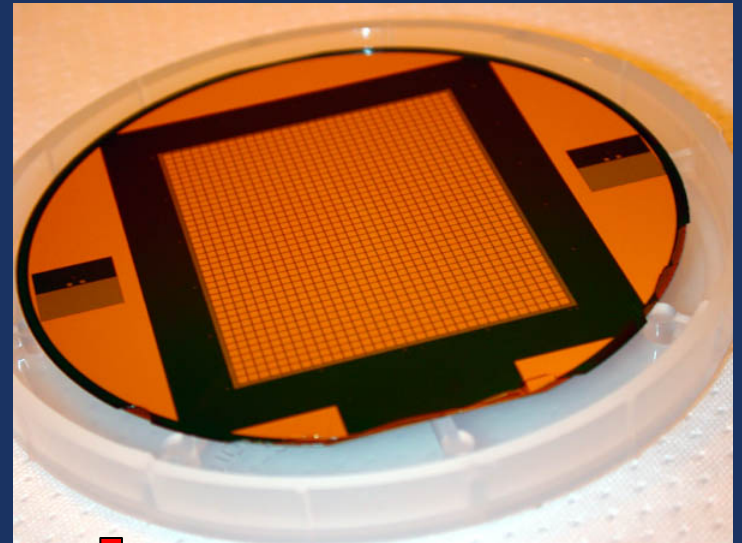
SQUID MUX pixels



SCUBA-2

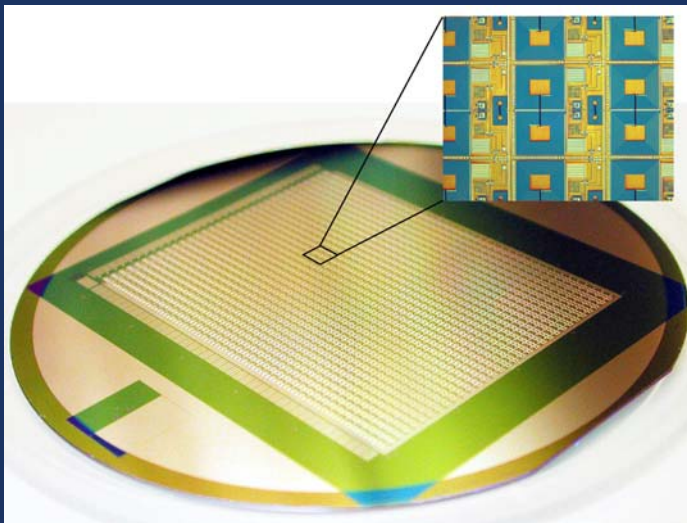


1,280-pixel TES bolometer

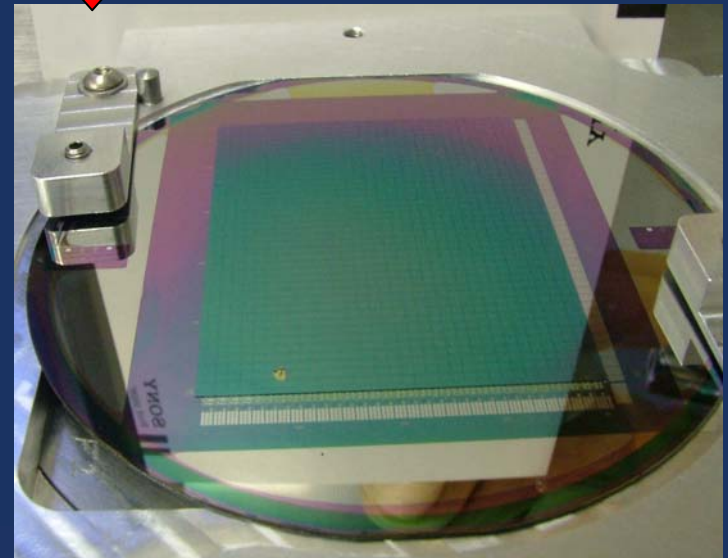


- A collaboration of the UK, Canada, and NIST
- SCUBA-2 will consist of 10,240 TES bolometer pixels (half at 450 μm , half at 850 μm) on the

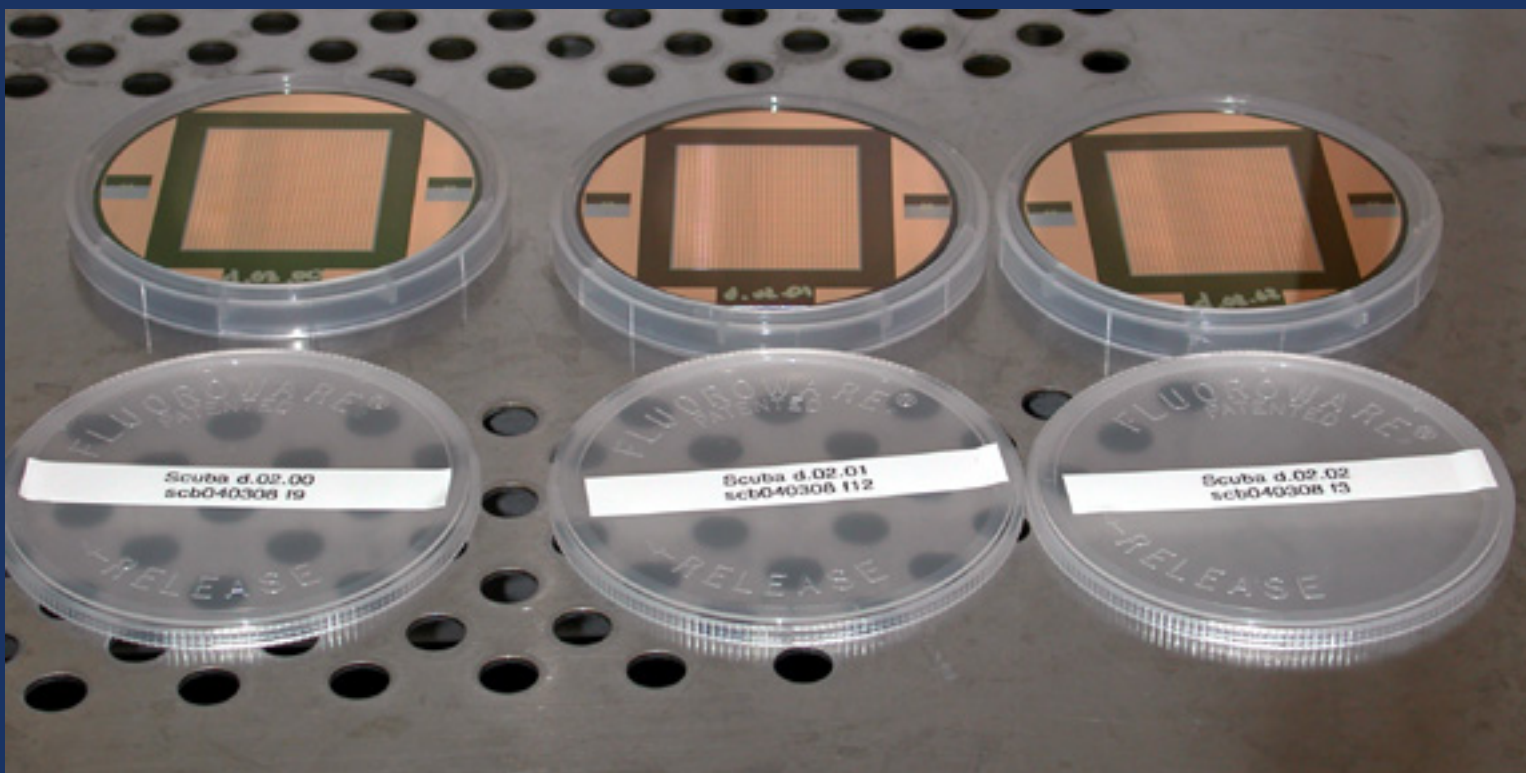
1,280-pixel SQUID Multiplexer



bump-bonded subarray (TES+MUX)

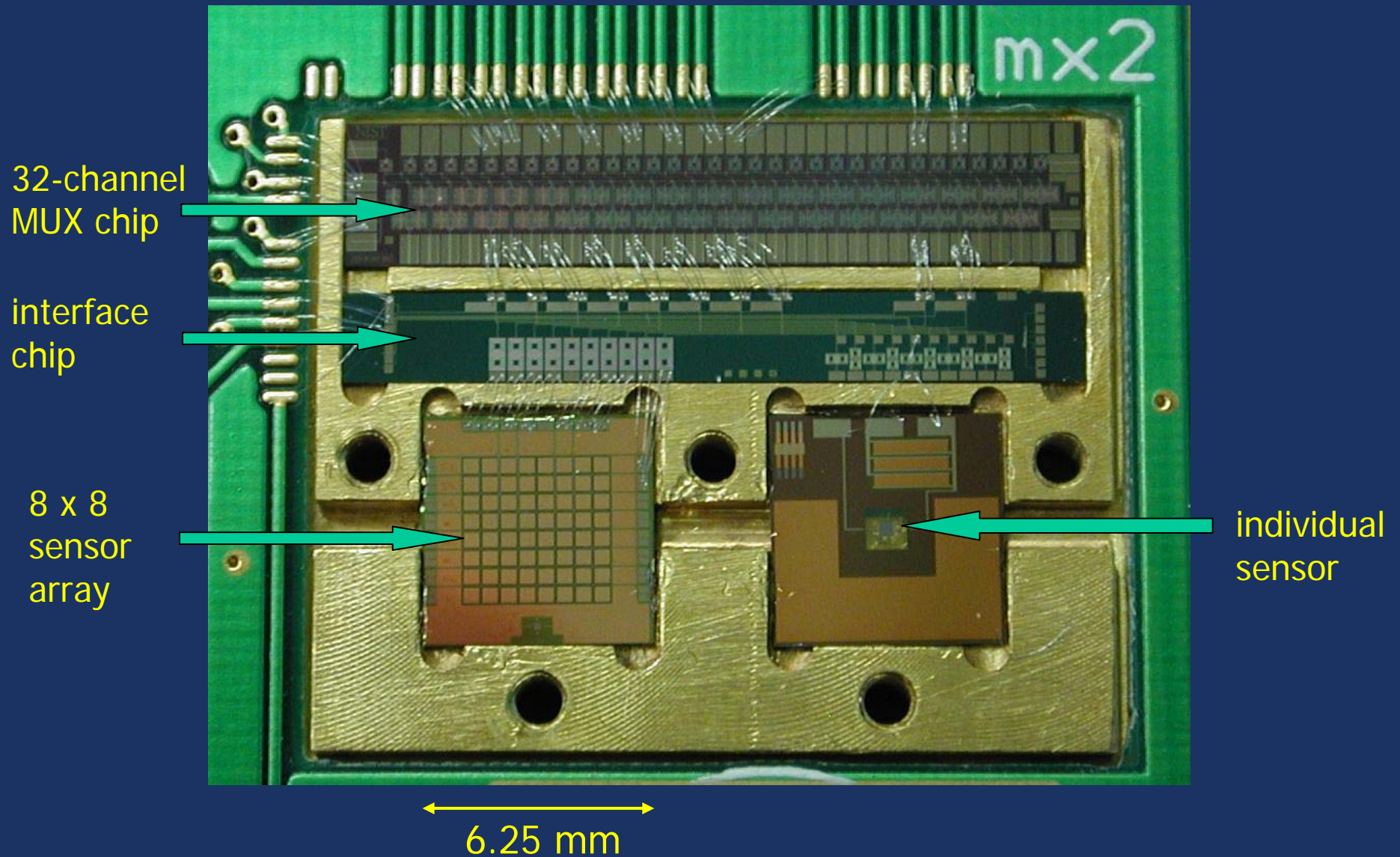


Manufacturability



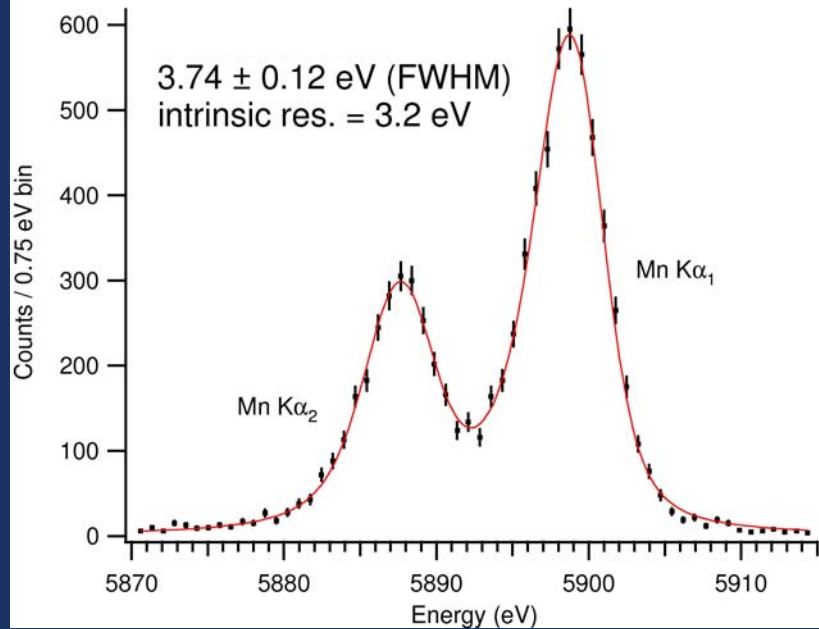
We are fabricating eight 1,280-pixel THz arrays for SCUBA-2

Multiplexed x-ray arrays

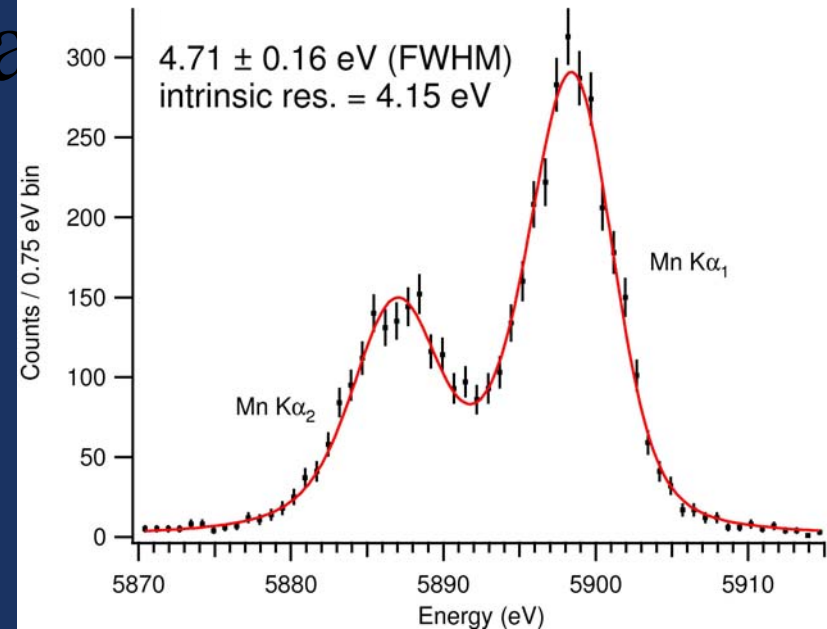


Multiplexed x-ray calorimeter results

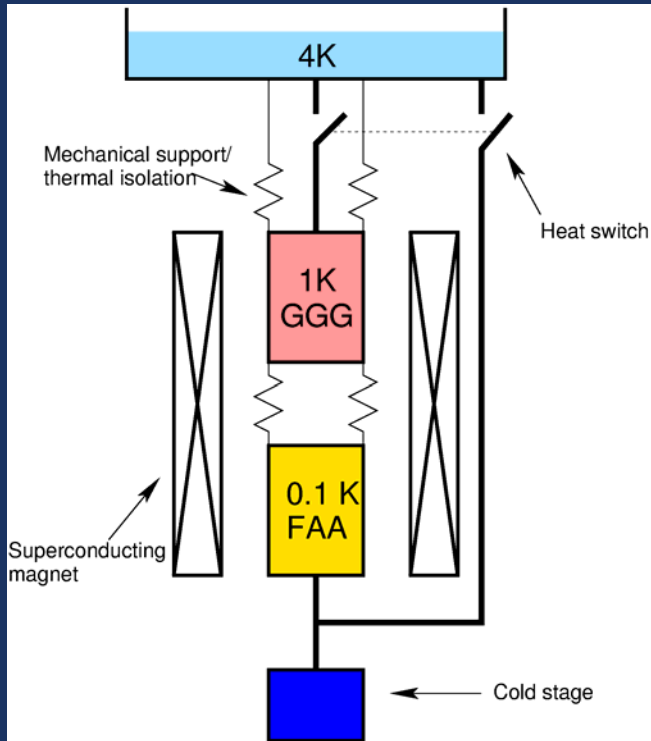
8-channel TDM



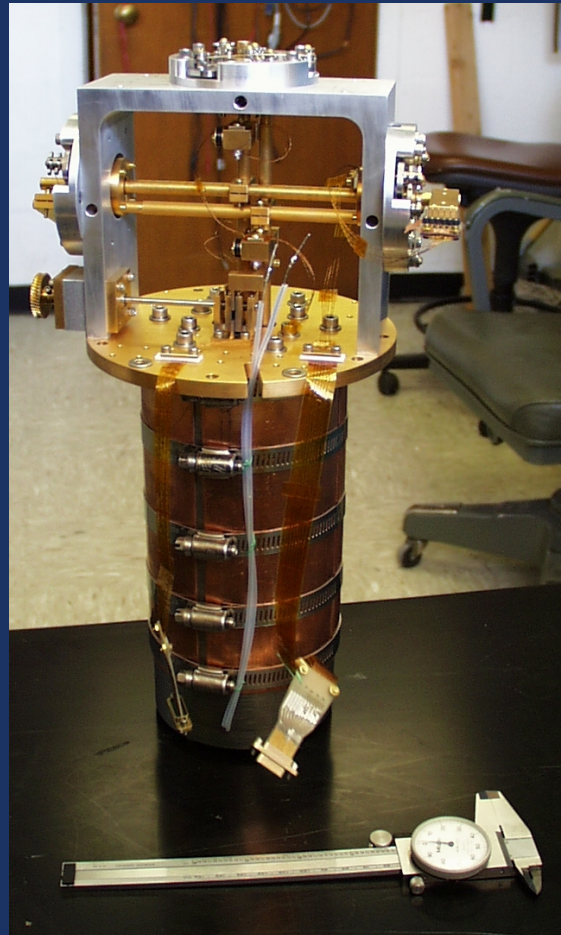
16-channel TDM



100 mK cryogenics



2-stage adiabatic demagnetization refrigerator (ADR)



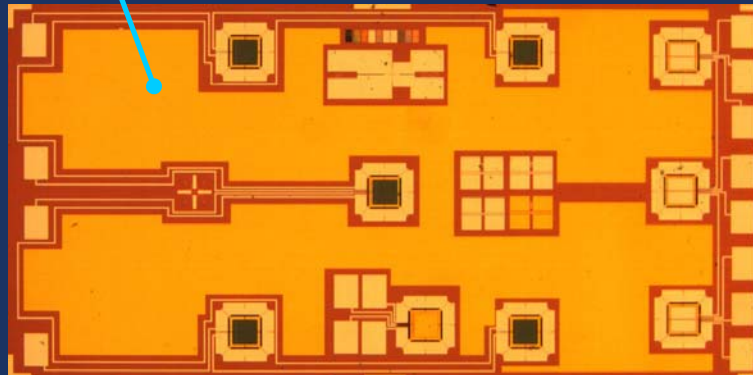
ADR and cryogen vessels mounted on SEM

Currently assembling a compact, cryogen-free ADR system compatible with modern SEMs

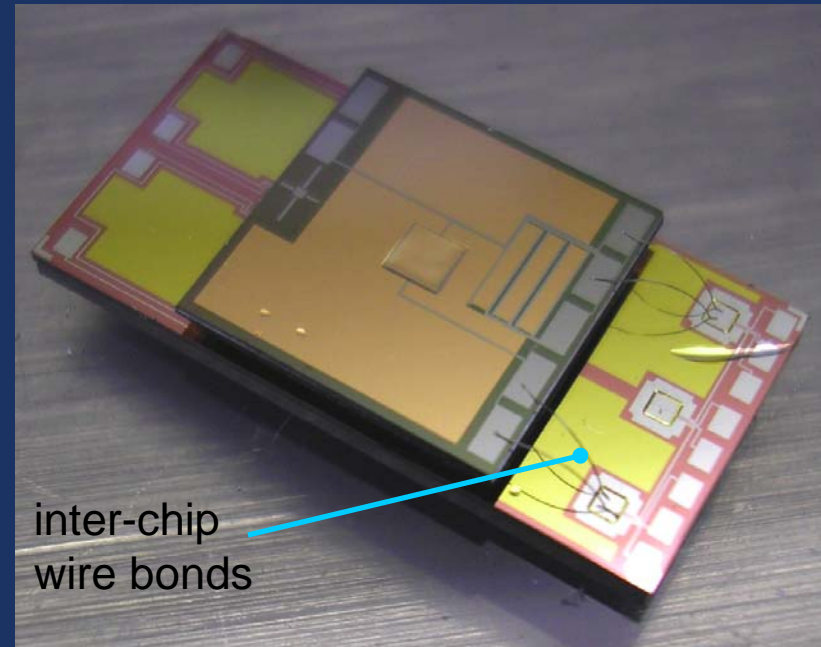
Each magnet cycle gets you to ~ 55 mK and ~ 24 hours < 100 mK

NIS full chip cooling

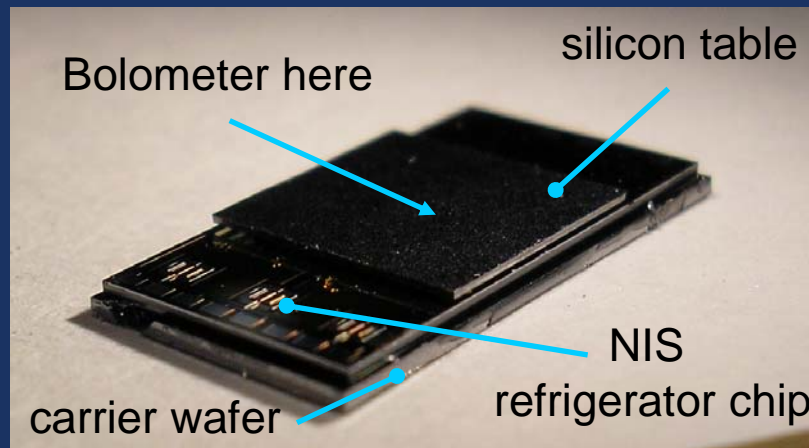
NIS refrigerator chip



12.5 mm



inter-chip wire bonds



Bolometer here

silicon table

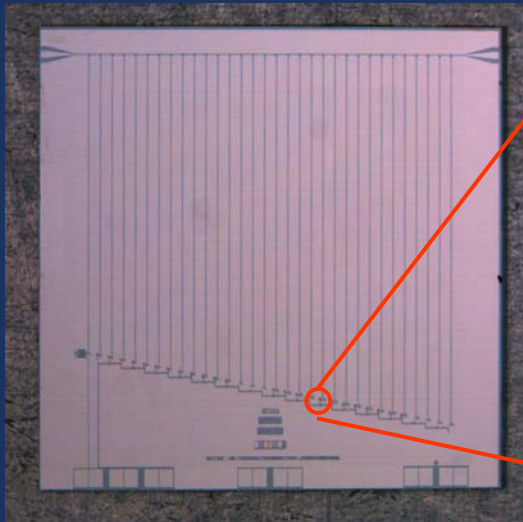
carrier wafer

NIS refrigerator chip

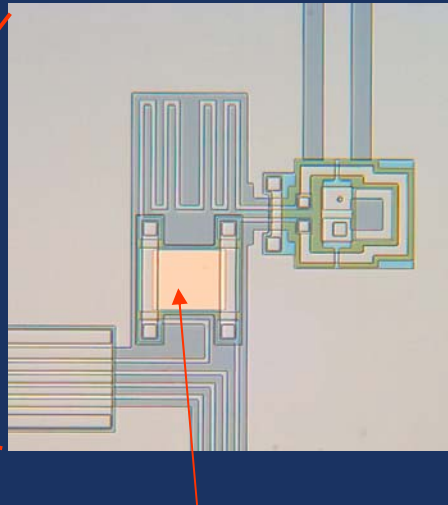
- Like a superconducting Peltier cooling
- Allows ADR temperatures from a cheap, robust, commercial He-3 refrigerator (~ 20 k\$)

Microwave SQUID multiplexers

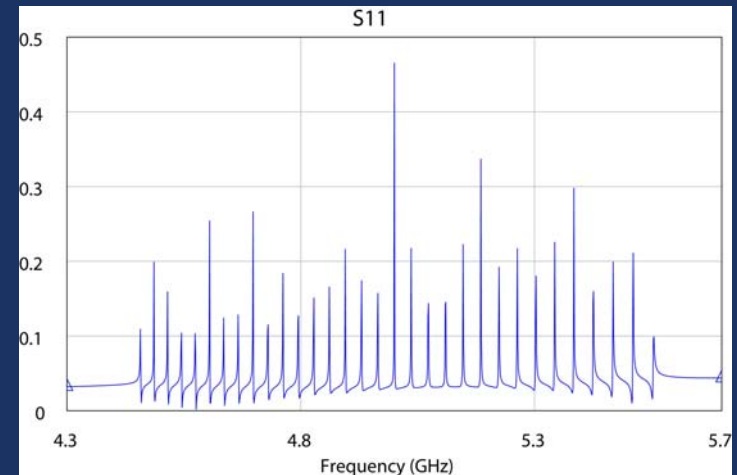
Chip with 32 microwave SQUIDs



Closeup of one SQUID



Model of response of 32 SQUIDs (data to follow)



Resistor simulates TES

- Many SQUIDs / bolometers coupled to high-Q resonators
- Possible future pathway to much larger arrays – 100,000+ pixels
- Scalable to >10,000 pixels in one output channel with large per-pixel bandwidth
- One output cable + one HEMT amplifier for thousands of pixels

Development possible over 5-10 years

All pixels 250 μm in size...

Optimization	E	ΔE_{FWHM}	array size	Array count rate	Timescale
Best resolution	0.1 – 10 keV	3 eV	32 \times 32	200 kHz	~ 3 years
Best count rate 1 keV	0.1 – 1 keV	6 eV	100 \times 100	20 MHz	~ 5 years
Best count rate 10 keV	0.1 – 10 keV	20 eV	100 \times 100	5 MHz	~ 5 years
Microwave	0.1 – 10 keV	5 eV	100,000	100 MHz	5 - 10 years

Can also make instruments for THz, IR, visible & UV, γ -ray